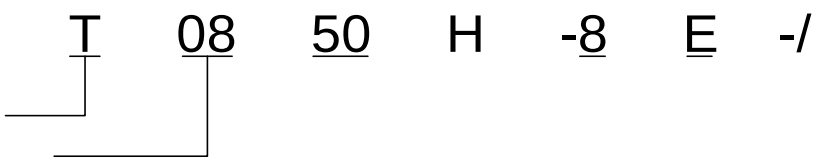
ORDERING INFORMATION



TTdx<03C6>Tj56.64 795.2-0.007[Tc 0.007[Tw 1.013[(TTdx [+)-13.7 (86)]TJ

FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

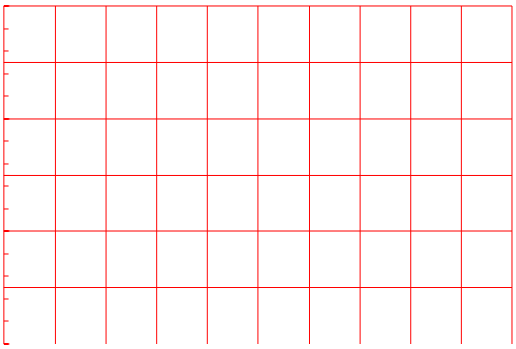
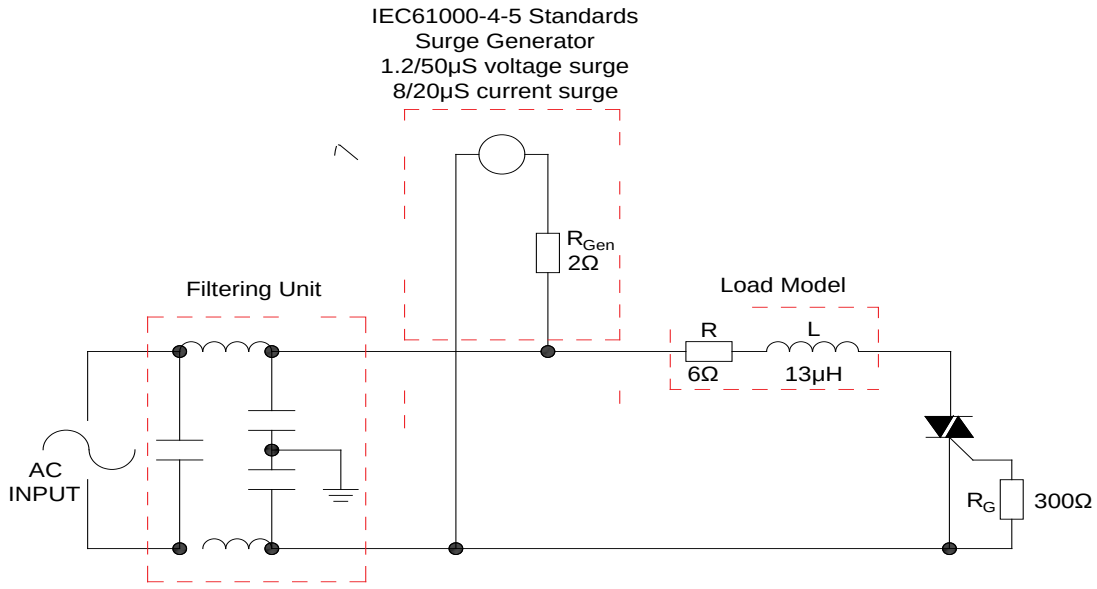


FIG.8 Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3 /sec. Max

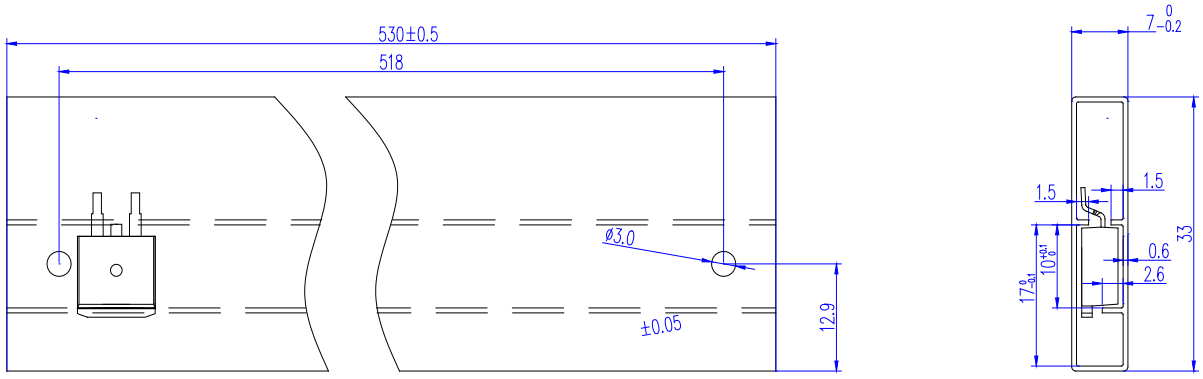
$T_{s(max)}$ 5(57.345 0.56 111.72 384.48Tj -0 Tap r Tw ( )Tj EMC / Tw 1.443 Tw 10.56 0 0 1343 Twr70 0 Cup.3 (x)) R

T0850H-8E

PACKAGE MECHANICAL DATA

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.40		9.60	0.370		0.378
D	2.40			0.094		
E	1.20		1.50	0.047		0.059
F	0.75		0.85	0.029		0.033

DELIVERY MODE



PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	5,000

Dimensions						
Ref.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	23.70	24.00	24.30			
E	1.65	1.75	1.85			
F	11.40	11.50	11.60			
D0	-	1.50	1.60			
D1		1.50	1.60			
P0	3.90	4.00	4.10			
P1	15.90	16.00	16.10			
P2	1.90	2.00	2.10			
A0		10.90	11.-5 (6.)4.9 (00)-1661.85			
B0						
K0						
t						